



Integrated Device Technology, Inc.
6024 Silver Creek Valley Road, San Jose, CA - 95138

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: **A1304-01** Date: April 29, 2013
 Product Affected: LDS6120PVG1, LDS6120PVG18
 built in SSOP-48
 Date Effective: July 29, 2013

MEANS OF DISTINGUISHING CHANGED DEVICES:
 Product Mark Lot # will have "P" prefix
 Back Mark
 Date Code
 Other

Contact: IDT PCN DESK
 E-mail: pcndesk@idt.com

Attachment: Yes No
 Samples: Samples are available now.

DESCRIPTION AND PURPOSE OF CHANGE:

- Die Technology
- Wafer Fabrication Process
- Assembly Process
- Equipment
- Material
- Testing
- Manufacturing Site
- Data Sheet
- Other

This notification is to advise our customers that IDT is adding Amkor, Philippines (ATP) as an alternate assembly facility for device type LDS6120PVG1 and LDS6120PVG18. Presently, ATP is a qualified assembly facility for SSOP package family.

There is no change to the moisture performance.

RELIABILITY/QUALIFICATION SUMMARY:

There is no expected change to the product quality and reliability.

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.

IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: _____ *Approval for shipments prior to effective date.*

Name/Date: _____ E-Mail Address: _____

Title: _____ Phone# /Fax# : _____

CUSTOMER COMMENTS:

IDT ACKNOWLEDGMENT OF RECEIPT:

RECD. BY: _____ DATE: _____



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ATTACHMENT 1 - PCN # : A1304-01

PCN Type: Alternate Assembly Location

Data Sheet Change: None. No change in moisture sensitivity level (MSL).

Detail Of Change:

This notification is to advise our customers that IDT is adding Amkor, Philippines (ATP) as an alternate assembly facility for device types LDS6120PVGI and LDS6120PVGI8. Presently, ATP is a qualified assembly facility for SSOP package family.

The material set details of the current Assembly location is shown in the table below. The die attach used at ATP is qualified IDT material. There is no change from the existing qualified lead frame material, lead finish, mold compound and wire for this alternate assembly site.

There is no change to the moisture performance using the assembly material sets as listed in the below table.

Qualified Material Sets, by Assembly Subcontractor

Description	Existing	Add
Assembly Location	PT Unisem, Indonesia	Amkor, Philippines
Assembly Materials	Die Attach: CRM1076NS	Ablestik 8290
	Wire: Au Wire	Au Wire
	Mold Compound: G600	G600
	Lead Frame: Copper Alloy	Copper Alloy
	Plating: Matte 100% Sn	Matte 100% Sn



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ATTACHMENT 1 - PCN # : A1304-01

Qualification Information and Qualification Data:

Qualification Test Plans and Results :

Qual Plan & Results: The qualification was performed in accordance with JEDEC47 recommended tests

Qual Vehicle: Device 9P946AFLF SSOP-48 (3 lots)

Test Description	Test Method	Test Results (SS / Rej)		
		Lot 1	Lot 2	Lot 3
* HAST - biased (130 °C/85% RH, 100 Hrs)	JESD22-A110	25/0	25/0	25/0
* Temperature Cycle / Condition B (-55 °C to +125 °C, 700 Cyc)	JESD22-A104	25/0	25/0	25/0
* Pressure Cooker (121 °C / 2 ATM, 168 hours)	JESD22-A102	25/0	25/0	25/0
High Temp. Storage Test (150 °C, 1000 Hrs)	JESD22-A103	25/0	25/0	25/0

Note:

* Test requires moisture pre-conditioning sequence per JESD22-A113 prior to stress test